



HYSOL®EO1073

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PRODUCT DESCRIPTION

Hysol® EO1073 is an epoxy adhesive system designed for high adhesion and platability in electroless copper solutions. This highly thixotropic material is designed to maximize resin bleed on most metallic substrates.

TYPICAL APPLICATIONS

Electronic Adhesive

PROPERTIES OF UNCURED MATERIAL

Color	Black
Filler Content, % (ITM3A)	50
Shelf Life @ -40°C, (-40°F), months	9
Typical Value	
Viscosity (ITM2A)	
Brookfield RVF	
@ 25°C (77°F)	
Spindle 7, Speed 4, Cp	180,000

PHYSICAL PROPERTIES, CURED MATERIAL

Color	Black
Glass Transition (Tg), °C, (ITM65B)	118
Coefficient of Linear Thermal Expansion, In/in/°C, (ITM65B), (40-120°C), alpha 1	35 x 10 ⁻⁶

Handling

Gel Time @ 100°C, (212°F), minutes (ITM10N)	18
Recommended Dispense Needle	18 Gauge Taper Tip

Frozen storage at approximately 4°C or lower is recommended for maximum shelf life. Allow material to reach room temperature before use.

GENERAL INFORMATION

For safe handling information on this product, consult the Material Safety Data Sheet, (MSDS).

This product is not recommended for use in pure oxygen and/or oxygen rich systems and should not be selected as a sealant for chlorine or their strong oxidizing materials

Cure Schedule

Recommended Cure	15 minutes @ 150°
Recommended In-Line Cure	Zone 1: 30 seconds @ 30°C
	Zone 2: 30 seconds @ 150°C
	Zone 3: 30 seconds @ 150°C
	Zone 4: 30 seconds @ 150°C

Use suggested cure conditions as general guidelines. Other cure conditions may yield satisfactory results.

Note

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Loctite Electronics

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